

Product Specification

XBLW XBL1509

150KHz 3A PWM Buck DC/DC Converter











Description

The XBL1509 is a monolithic IC designed for a step-down DC/DC converter, and own the ability of driving a 3A load without additional transistor. It saves board space. The external shutdown function can be controlled by logic level and then come into standby mode. The internal compensation makes feedback control having good line and load regulation without external design. Regarding protected function, thermal shutdown is to prevent over temperature operating from damage, and current limit is against over current operating of the output switch. If current limit function occurs and V FB is down below 0.5V, the switching frequency will be reduced.

The XBL1509 operates at a switching frequency of 150KHz thus allow smaller sized filter components than what would be needed with lower frequency switching regulators. Other features include a guaranteed ± 4 tolerance on output voltage under specified input voltage and output load conditions, and \pm 15% on the oscillator frequency.

The chips are available in a standard 8-lead SOP8 package.

Features

- ➤ 3.3V, 5V, 12V and Adjustable Output Version
- > Output Adjustable Voltage From 1.23V to 37V
- ➤ Fixed 150KHz Switching Frequency
- Voltage Mode Non-synchronous PWM Control
- > ON/OFF Shutdown Control Input
- Wide 4.5V to 40V Input Voltage Range
- Output Load Current: 3A
- Low Power Standby Mode
- > Built-in Switching Transistor on Chip



SOP-8

Application

- Simple High-Efficiency Step-down Regulator
- On-card Switching Regulators
- Positive to Negative Converter



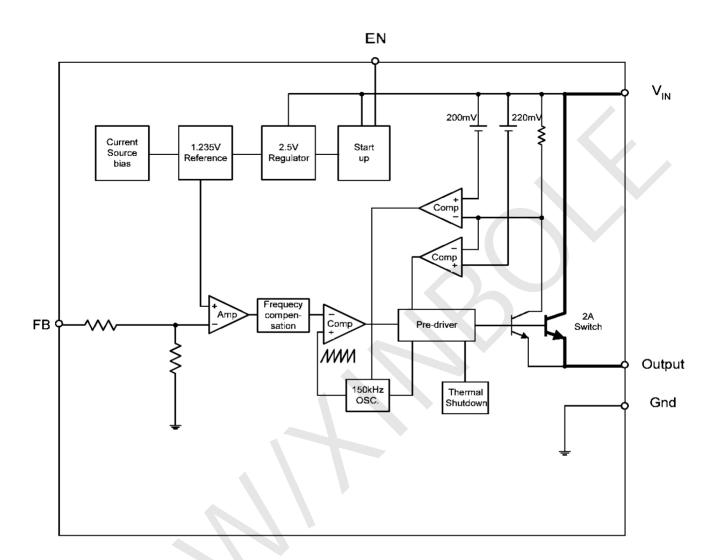
Ordering Information

ESOP-8

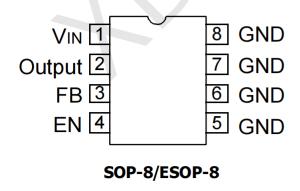
Product Model	Package Type	Marking	Packing	Packing Qty
XBLW XBL1509-3.3	SOP-8	1509-3.3	Tape	2500Pcs/Reel
XBLW XBL1509-5.0	SOP-8	1509-5.0	Tape	2500Pcs/Reel
XBLW XBL1509-12	SOP-8	1509-12	Tape	2500Pcs/Reel
XBLW XBL1509-ADJ	SOP-8	1509-ADJ	Tape	2500Pcs/Reel
XBLW XBL1509E-3.3	ESOP-8	1509E-3.3	Tape	2500Pcs/Reel
XBLW XBL1509E-5.0	ESOP-8	1509E-5.0	Tape	2500Pcs/Reel
XBLW XBL1509E-12	ESOP-8	1509E-12	Tape	2500Pcs/Reel
XBLW XBL1509E-ADJ	ESOP-8	1509E-ADJ	Tape	2500Pcs/Reel



Block Diagram



Pin Configuration



Pin Descriptions

Name	Description
V _{IN}	Supply Voltage Input
Output	Power Switching Output
GND	Ground
FB	Output Voltage Feedback Control
EN	ON/OFF Shutdown



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply Voltage	V _{IN}	+40	V
ON/OFF pin input voltage	V _{SD}	-0.3 ∼ V _{IN}	V
Feedback pin voltage	V _{FB}	-0.3 ~ VIN	V
Output voltage to ground	Vout	-1	V
Power dissipation	PD	Internally limited	W
Storage temperature	Tstg	-65 ~ +150	°C
Operating temperature	Topr	-40 ~ +125	°C
Operating voltage	V _{OP}	+4.5 ~ +40	V

Electrical Characteristics

(Refer to the test circuit, V_{IN} =12V for 3.3V, 5V, adjustable version and V_{IN} =24V for the 12V version, I_{LOAD} =0.5A)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Feedback Bias Current	I _{FB}	V _{FB} =1.3V (Adjustable version only)		50	100	nA
Oscillator Frequency	Fosc		127	150	173	kHz
Saturation Voltage	V _{SAT}	I _{OUT} =2A, No outside circuit V _{FB} =0V force driver on		1.2	1.5	V
Max. Duty Cycle(ON)	DC	V _{FB} =0V force driver on	93	98		
Min. Duty Cycle(OFF)		V _{FB} =12V force driver off		0		%
Current Limit	I _{CL}	Peak current, No outside circuit V _{FB} =0V force driver on	3.0	4.0		Α
Output Leakage Current (Output=0)	IL	No outside circuit V _{FB} =12V force driver off			2	mA
Output Leakage Current (Output=-1)	IL.	V _{IN} =40V		5	20	mA
Quiescent Current	I_Q	V _{FB} =12V force driver off		5	10	mA
Standby Quiescent Current	I_{STBY}	ON/OFF pin=5V V _{IN} =40V		50	200	μA
ON/OFF pin Logic Input	V_{IL}	Low(regulator ON)			0.6	
Threshold Voltage	V _{IH}	High(regulator OFF)	2.0			V
ON/OFF pin Logic Input Current	I _H	V _{LOGIC} =5.0V(OFF)		12	30	
ON/OFF pin Input Current	IL	V _{LOGIC} =0.5V(ON)		0	10	μA
Thermal Resistance	Өзс	Junction to case		15		°C/W
Thermal Resistance with Copper Area of Aapproximately 3 in ²	Өза	Junction to ambient		70		°C/W



Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
XBL1509-ADJ	·					
		4.5V≤V _{IN} ≤40V				
Output Feedback	V_{FB}	0.2A≤I _{LOAD} ≤3A	1.193	1.230	1.267	V
		V _{OUT} programmed for 3V				
Efficiency	η	V _{IN} =12V, I _{LOAD} =3A		74		%
XBL1509-3.3						
	V _{out}	4.75V≤V _{IN} ≤40V	3.168	3.300	3.432	V
Output Voltage	VOUI	0.2A≤I _{LOAD} ≤3A	3.100	3.300	3.432	V
Efficiency	η	V _{IN} =12V, I _{LOAD} =3A		76		%
XBL1509-5.0						
	V _{out}	7V <v<sub>IN<40V</v<sub>	4.80	5.00	5.20	V
Output Voltage	VOUT	0.2A≤I _{LOAD} ≤3A	4.60	3.00	3.20	V
Efficiency	η	V _{IN} =12V, I _{LOAD} =3A		83		%
XBL1509-12						
Output Voltage	V _{OUT}	15V≤V _{IN} ≤40V	11.52	12.00	12.48	V
Output voltage	VOUT	0.2A≤I _{LOAD} ≤3A	11.52	12.00	12.70	V
Efficiency	η	V _{IN} =25V, I _{LOAD} =3A		90		%

Function Description

Pin Function +VIN

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be presented at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

Ground

Circuit ground.

Output

Internal switch. The voltage at this pin switches between ($+V_{IN}-V_{SAT}$) and approximately -0.5V, with a duty cycle of approximately V_{OUT} / V_{IN} . To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be minimized.

Feedback

Senses the regulated output voltage to complete the feedback loop.

ΕN

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150uA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V shuts the regulator down. If this shutdown feature is not needed, the EN pin can be wired to the ground pin.



Thermal Considerations

The SOP8 package needs a heat sink under most conditions. The size of the heatsink depends on the input voltage, the output voltage, the load current and the ambient temperature. The XBL1509 junction temperature rises above ambient temperature for a 3A load and different input and output voltages. The data for these curves was taken with the XBL1509 (SOP8 package) operating as a buck-switching regulator in an ambient temperature of 25°C(st ill air). These temperature increments are all approximate and are affected by many factors. Higher ambient temperatures requires more heat sinker. For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout. (One exception is the output (switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat(lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further. Package thermal resistance and junction temperature increments are all approximate. The increments are affected by a lot of factors. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are, trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical sizetype of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.

Schottky Diode Selection Table

Current	Surface Mount	Through Hole	VR (The same as system maximum input voltage)					
			20V	30V	40V	50V	60V	
1A		1	1N5817	1N5818	1N5819			
		1	1N5820	1N5821	1N5822			
		4	MBR320	MBR330	MBR340	MBR350	MBR360	
	1		SK32	SK33	SK34	SK35	SK36	
2 and 24	1			30WQ03	30WQ04	30WQ05		
2 and 3A		√		31DQ03	31DQ04	31DQ05		
		√	SR302	SR303	SR304	SR305	SR306	



XBL1509 Series Buck Regulator Design Procedure (Adjustable Output)

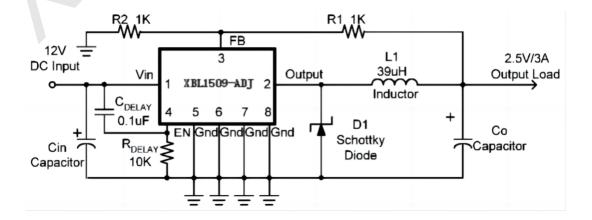
	Throug	h Hole Output El	ectrolytic	Surface Mount Output Capacitor			
Output Voltage (V)	Panasonic HFQ Series (uf/V)	Nichicon PL Series (uf/V)	Feedforward Capacitor	AVX TPS Series (uf/V)	Sprague 595D Series (uf/V)	Feedforward Capacitor	
2	820/35	820/35	33nf	330/6.3	470/4	33nf	
4	560/35	470/35	10nf	330/6.3	390/6.3	10nf	
6	470/25	470/35	3.3nf	220/ 10	330/ 10	3.3nf	
9	330/25	330/25	1.5nf	100/ 16	180/ 16	1.5nf	
12	330/25	330/25	1nf	100/ 16	180/ 16	1nf	
15	220/25	220/35	680pf	68/20	120/20	680pf	
24	220/35	150/35	560pf	33/25	33/25	220pf	
28	100/50	100/50	390pf	10/35	15/50	220pf	

XBL1509 Series Buck Regulator Design Procedure (Fixed Output)

	Condition		Inductor	Output Capacitor (COUT)				
	Conditio	ons	(L1)	Through Hole	Electrolytic	Surface Mount Tantalum		
Output Voltage (V)	Load Current (A)	Max Input Voltage (V)	Inductance (uh)	Panasonic HFQ Series (uf/V)	Nichicon PL Series (uf/V)	AVX TPS Series (uf/V)	Sprague 595D Series (uf/V)	
(-)	(-,	6	22	470/25	470/35	330/6.3	390/6.3	
3.3	2 and 3	10	33	330/35	330/35	330/6.3	390/6.3	
		40	47	330/35	270/50	220/ 10	330/ 10	
		9	22	470/25	560/ 16	220/ 10	330/ 10	
5	2 and 3	20	68	180/35	180/35	100/ 10	270/ 10	
		40	68	180/35	180/35	100/ 10	270/ 10	
		15	33	330/25	330/25	100/ 16	180/ 16	
12	2 and 3	20	68	180/25	180/25	100/ 16	120/20	
		40	150	82/25	82/25	68/20	68/25	

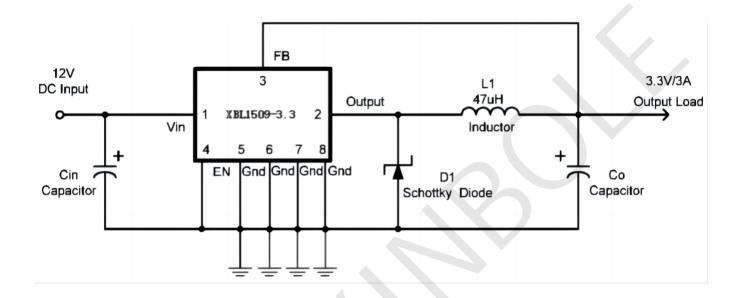
Application Circuit

Delay Start Circuit

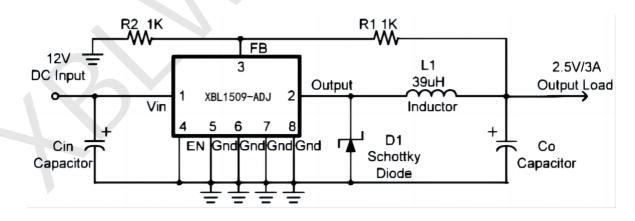




Fixed Type Circuit



Adjustable Type Circuit



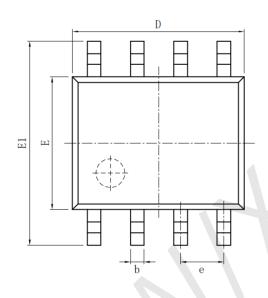
Vout =
$$V_{FB} \times (1 + \frac{R1}{R2})$$

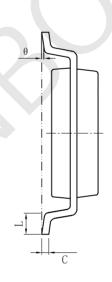
 $V_{FB} = 1.23V$
 $R2 = 1K \sim 3K$

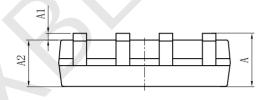


• SOP-8

Size	Dimensions I	n Millimeters	Size	Dimensions	In Inches
Symbol Symbol	Min(mm)	Max(mm)	Symbol	Min(in)	Max(in)
A	1. 350	1. 750	A	0. 053	0.069
A1	0. 100	0. 250	A1	0.004	0.010
A2	1. 350	1. 550	A2	0.053	0.061
b	0.330	0. 510	b	0.013	0.020
С	0.170	0.250	С	0.006	0.010
D	4.700	5. 100	D	0.185	0.200
Е	3.800	4.000	Е	0.150	0. 157
E1	5.800	6.200	E1	0.228	0. 224
е	1. 2	270 (BSC)	е	0.0	50 (BSC)
L	0. 400	1. 270	L	0.016	0.050
θ	0°	8°	θ	0°	8°









· ESOP-8

Symbol A		Williamstone		Dimonoion	a In Inches
A	Dimensions In		Size		s In Inches
	Min(mm)	Max(mm)	Symbol	Min(in)	Max(in)
	1. 350	1.750	A	0.053	0.069
A1	0. 050	0. 150	A1	0.004	0.010
A2	1. 350	1.550	A2	0.053	0.061
b	0.330	0.510	b	0.013	0.020
С	0.170	0.250	С	0.007	0.010
D	4.700	5. 100	D	0. 185	0. 201
D1	3. 202	3.402	D1	0.126	0. 134
Е	3.800	4.000	Е	0.150	0. 157
E1	5.800	6. 200	E1	0. 228	0. 244
E2	2. 313	2. 513	E2	0.091	0.099
e		0 (BSC)	e	0.001	050 (BSC)
L	0. 400	1. 270	L	0. 016	0.050
θ	0° 400	8°	θ	0. 016	8°
E1	d d d d d d d d d d d d d d d d d d d	e		93	



Statement:

- XBLW reserves the right to modify the product manual without prior notice! Before placing an order, customers need to confirm whether the obtained information is the latest version and verify the completeness of the relevant information.
- Any semi-guide product is subject to failure or malfunction under specified conditions. It is the buyer's responsibility to comply with safety standards when using XBLW products for system design and whole machine manufacturing. And take the appropriate safety measures to avoid the potential in the risk of loss of personal injury or loss of property situation!
- XBLW products have not been licensed for life support, military, and aerospace applications, and therefore XBLW is not responsible for any consequences arising from the use of this product in these areas.
- If any or all XBLW products (including technical data, services) described or contained in this document are subject to any applicable local export control laws and regulations, they may not be exported without an export license from the relevant authorities in accordance with such laws.
- The specifications of any and all XBLW products described or contained in this document specify the performance, characteristics, and functionality of said products in their standalone state, but do not guarantee the performance, characteristics, and functionality of said products installed in Customer's products or equipment. In order to verify symptoms and conditions that cannot be evaluated in a standalone device, the Customer should ultimately evaluate and test the device installed in the Customer's product device.
- XBLW documentation is only allowed to be copied without any alteration of the content and with the relevant authorization. XBLW assumes no responsibility or liability for altered documents.
- XBLW is committed to becoming the preferred semiconductor brand for customers, and XBLW will strive to provide customers with better performance and better quality products.

XBLW Version2.0 11/11 www.xinboleic.com